

Electronic Patent Application Fee Transmittal

Application Number:	10715641
Filing Date:	18-Nov-2003
Title of Invention:	RAISED SOLDER-MASK-DEFINED (SMD) SOLDER BALL PADS FOR A LAMINATE ELECTRONIC CIRCUIT BOARD
First Named Inventor/Applicant Name:	Tz-Cheng Chiu
Filer:	Wade J. Brady III/Jackie McBride
Attorney Docket Number:	TI-36052

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Certificate of correction	1811	1	100	100
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Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				100